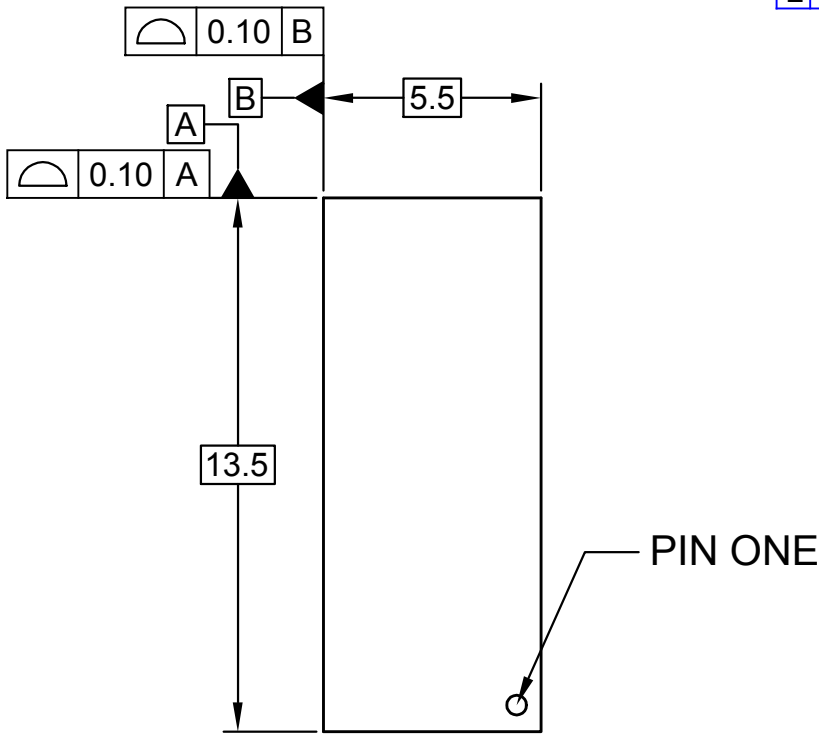
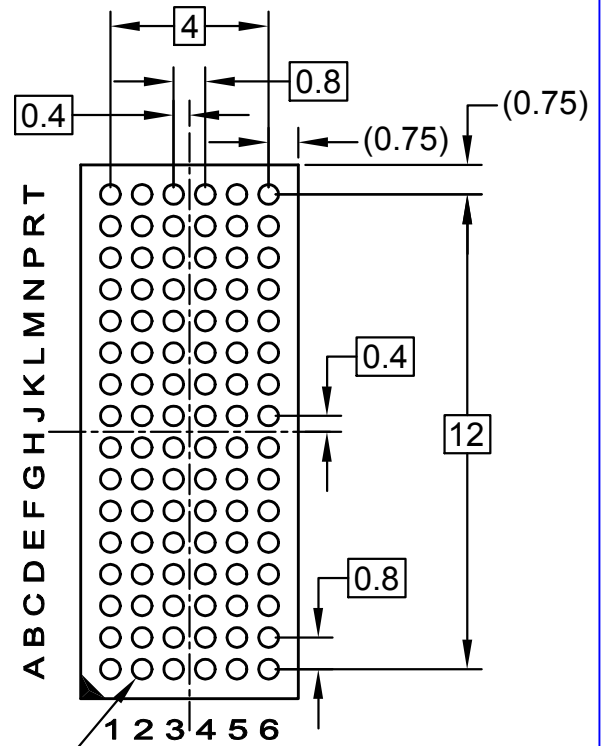


REVISIONS

LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
0	INITIAL DRAWING	NA	6-25-99	H.ALLEN
A	ADDED LANDPATTERN REC.	NA	1-26-00	H.Allen
B	CORRECTED PKG THICK DIM RELEASED TO DOC. CONTROL	NA	6-13-00	H.Allen
C	Entered Ball location tolerance	NA	8-24-00	J. Kingsbury
D	Assigned Top and Bottom names	ECN-MKT-BGA96revD	05-09-01	J. Kingsbury
E	Changed Revision level only	ECN-MKT-BGA96ArevE	06-07-01	J. Kingsbury



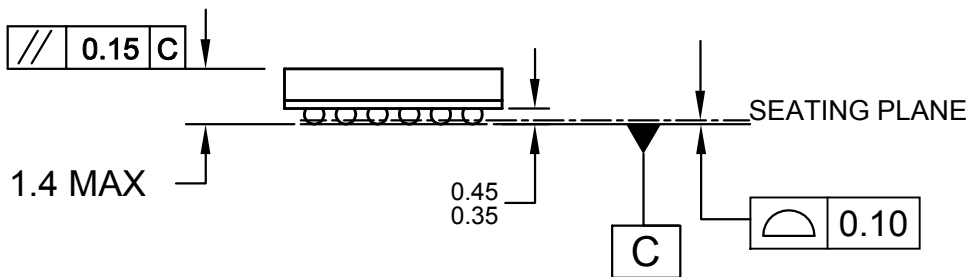
Top View



Bottom View

96X 0.5^{+0.05}_{-0.05}

⊕	0.15(M)	C	A	B
	0.08(M)	C		



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA96ArevE

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR	333 Western Ave. S. Portland, Maine		
DRAWN H. Allen	6-25-99			96BALL, FBGA, JEDEC M0-205, 5.5MM WIDE	
DFTG. CHK J.Kingsbury	01-24-01				
ENGR. CHK J.Kingsbury	01-24-01				
		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-BGA96A	REV E
		DO NOT SCALE DRAWING		SHEET 1 of 1	